COMPARISON OF CREEP BEHAVIOUR AND MICROSTRUCTURAL CHANGES
IN ELECTRODEPOSITED ULTRAFINE-GRAINED NICKEL AND ITS PARTICLE-REINFORCED
NANOCOMPOSITE

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Abstract

On the basis of the creep experimental results the paper reports comparison creep behaviour of electrodeposited ultrafine-grained nickel and its particle-reinforced nanocomposite. The objective of this research was to further improve the knowledge of the creep behaviour of monolithic nickel and to explore the role of nano-sized SiO₂ particles in the potential creep strengthening of electrodeposited Ni nanocomposite. The creep behaviour and microstructure of the pure ultrafine-grained nickel and its nanocomposite reinforced by 2 vol.% nano-sized SiO₂ particles were studied at temperatures in the range from 293 to 573 K and at the tensile stresses between 100 to 800 MPa. It was found that the creep resistance of the nanocomposite might be noticeably improved compared to the monolithic nickel. Possible creep mechanisms controlling the creep rate during the creep loading were discussed. The Coble creep as creep rate controlling mechanism was founded improbable.

Keywords:
Creep, ultrafine-grained Ni, nanocomposite, electrodeposition.

1. INTRODUCTION

he success of nanostructured metal electrodeposits in the area of nanostructured materials accelerated research efforts and the development of applications in various industrial sectors. Several review articles on the electrodeposition methods have been published over past decade [1-3]. Furthermore, there are numerous reports in the literature that dealt with electrodeposits with very small crystal size and the mechanical property enhancements that can be achieved in such materials by grain size reduction. However, the experimental results of different investigators are not consistent with each other [4]. The extrinsic effect of the complications is related to defects introduced in the processing of material, including high porosity level, large distribution of grain size and different impurity level. The intrinsic high activity due to large volume of intergranular components leads to unique deformation behaviour that may involve multiple mechanisms, and a single model may not be sufficient to interpret the deformation process. These effects render it difficult to identify the mechanisms responsible for differences in mechanical and/or creep properties.

Reduction of the grain size of a polycrystalline material can be successfully produced through advanced synthesis processes such as the electrodeposition (ED) technique and severe plastic deformation (SD) [5,6]. Although creep is an exceptionally old area of research, above-mentioned processing techniques have become available over the last two decades which provide an opportunity to expand the creep behaviour into new areas that were not feasible in earlier experiments. Creep testing of nanocrystalline (grain size d < 100 nm) and ultrafine-grained (d < 1 μm) materials is characterized by features that may be different from those documented for coarse-grained materials and thus cannot easily be compared. In fact, the creep behaviour
of ED nanostructured nickel has been investigated and the experimental results showed that the nanostructured nickel exhibited deformation behaviour, different from the counterpart coarse-grained nickel [4,7,8]. Nevertheless, data on the creep behaviour of nanocrystalline nickel not only are limited in scope but also are obtained under questionable experimental conditions [4]. However, very scarce creep experiments have been performed on ultrafine-grained nickel and its composite till now [9,10]. Due to the limited information, this study investigates the creep behaviour of ultrafine-grained ED nickel and its nanocomposite reinforced by SiO$_2$ particles. The aim is to gain further insight into which process(es) is (are) responsible for creep deformation.

2. EXPERIMENTAL MATERIALS AND PROCEDURES

The galvanostatic deposition of monolithic Ni with a purity of 99.95% and co-deposition of nano-sized SiO$_2$ particles under direct current on copper foil were carried out by a recently developed technique [11-13]. The SiO$_2$ nanopowder (Aerosil 300, Degussa AG, Germany) with a median particle size of about 21 nm, a geometric standard deviation of 1.1 and specific Brunauer-Emmett-Teller (BET) surface of 300 m$^2$/g was used for the production of a particle-reinforced nickel nanocomposite. The electrolyte used in this study was composed of 500 g/L (2 mol) nickel sulfamate Ni(SO$_4$NH$_2$)$_2$, 26 g/L boric acid H$_3$BO$_3$, and 8.5 g/L nickel chloride NiCl$_2$. The pH of the electrolyte was kept at 3.1. All chemicals are commercially available at Alfa Aesar. The co-deposition was carried out from this electrolyte containing 15 g of nanopowder per litre. The electrodeposition was conducted at a bath temperature of 298 K and the current density of 25 mA/cm$^2$. The deposition time varied among the deposits and resulted in the deposit thickness of 300-800 $\mu$m. According to the chemical analysis, both deposits exhibited less then 0.001 wt.% of S. The chemical composition of the nanocomposite was investigated using a Sollaar M6 atomic absorption spectrometer (AAS). The specimens were microwave-dissolved in a Multiwave 3000. The copper substrate was metallographic ground out after deposition to obtain the freestanding strips of the deposits. Dog-bone shaped creep specimens with a gauge length of 25 mm and a width of 3.5 mm were machined from these freestanding strips. The final thickness of the specimens was about 400 $\mu$m.

Constant stress uniaxial tensile creep tests were carried out at temperatures from 293 to 573 K and the applied stress ranged from 100 to 800 MPa. The creep tests were performed in purified argon using tensile creep testing machines, making it possible to keep the nominal stress constant to within 0.1% up to a true strain of about 0.35. The creep elongations were measured using a linear variable differential transducer, continuously recorded digitally and computer processed. The change in the actual gauge length of the specimen was measured with a sensitivity of 5 x 10$^{-6}$. Almost all the creep tests were run to the final fracture. Following electrodeposition and creep testing, samples were prepared for examination by transmission electron microscopy (TEM) in a Philips CM 12 TEM/STEM microscope.

3. EXPERIMENTAL RESULTS

3.1. Microstructural characterization

Fig.1 shows TEM bright-field images taken from the as-deposited pure nickel and its composite. The grain size distribution of pure nickel was very inhomogeneous and a number of grains were significantly larger than the average ultrafine grain size of ~200 nm. It should be stressed that the plating bath did not contain saccharin as a grain refiner. This is probably the cause of the relative coarse grain sizes obtained. Growth twins were found to be prevalent in the microstructure (Fig. 1a). By contrast, relatively homogeneous and fine microstructure compared with pure Ni was found for the particle-reinforced Ni-SiO$_2$ composite (Fig. 1b). The size of matrix grains ranges from ~ 40 nm to ~ 100 nm and an average grain size of 60 nm was estimated by quantitative image analysis. The nano-sized SiO$_2$ particles with an average size of 21 nm were homogeneously distributed in the nickel matrix. The amount of particles in the matrix and the particle distribution were analysed using the AAS methods. The composite specimens (10x10 mm) were cut into four experimental specimens (of 0.1g) and transformed into solutions, using microwave decomposition. The solutions were used to establish the wt.% of Si, which on the basis of stoichiometry was recalculated to wt.% of SiO$_2$. The average amount of SiO$_2$ particles in the composite was established as 1.31 wt.% with a standard deviation of 0.25 [14].
The microstructure of both pure nickel and composite specimens after creep testing at room temperature and 373 K did not show any noticeable grain growth. On the other hand, the post-creep specimens of pure nickel that had been tested at temperature of 473 K exhibited a substantial increase in grain size observed by TEM in both the grip and the gauge sections as shown in Fig. 2a. Thus, the microstructural changes were caused by thermal exposure rather than by creep loading. At the same temperature the nanocomposite appeared to be more stable in its grain size, however, in Fig. 2b it is clearly seen that grain growth of individual grains had taken place in the nanocomposite matrix, too. Thus, the addition of SiO$_2$ particles mostly situated at the grain interiors cannot fully inhibit grain growth by the pinning the boundaries of the matrix nickel grains. In both electrodeposits the microstructure after creep exposure at 473 K consists of a duplex structure of very small and large grains (Fig. 2). The pronounced thermal instability of the microstructure of the unreinforced nickel was the reason for leaving out its creep testing at 573 K.

3.2. Creep behaviour in the as-deposited ultrafine-grained pure nickel and its nanocomposite

A summary of creep data is shown in Figs. 3a and b: all of these double logarithmic plots were obtained at temperatures 293 – 573 K over a broad range of applied stress, and they show the stress dependences of (a) the minimum creep rate, $\dot{\varepsilon}_{\text{min}}$, and (b) the time to fracture, $t_f$. Several conclusions may be reached from
inspection of these data. In general, the composite exhibits a better creep resistance than the unreinforced nickel especially at low testing temperatures. As can be seen from Fig. 3a at 373 K there is an order of

![Graph](image)

**Fig. 3.** Stress dependence of (a) the experimental minimum creep rates and their comparison with theoretical model for Coble creep, and (b) the times to fracture for both electrodeposits.

magnitude difference in the minimum creep rate and the time to fracture between both the two electrodeposits. Nevertheless, the data for the composite at room temperature in Fig. 3 are insufficient to make a general conclusion. They are limited to an extremely narrow stress interval of the testing conditions as a result of very high stress sensitivity of the minimum creep rate and the creep lifetime of the composite. It should be mentioned that pronounced thermal instability manifested by grain growth and/or by dynamic recrystallization, which results in local structure coarsening leading to bimodal grain structures at higher temperatures limit the tested temperature range. Further, as depicted from a comparison of Figs. 3a and b, the slopes and therefore the apparent stress exponents of the minimum creep rate \( n = \frac{\partial \ln \dot{\varepsilon}}{\partial \ln \sigma} \) and the time to fracture \( m = \frac{\partial \ln t_f}{\partial \ln \sigma} \) for the unreinforced nickel are similar and the values of those exponents consistently decrease while increasing the testing temperature. Considering the testing limitation and based on the creep tests carried out for different values of the applied stress and testing temperatures the values of stress exponents \( n \) of the minimum creep rate were evaluated. For pure nickel they were found to be in the range from \( n \approx 46 \) for 293 K to \( n \approx 6 \) for 473 K. The Ni-SiO\(_2\) nanocomposite exhibited values of stress exponent \( n \approx 47 \) for 293 K, and \( n \approx 5 \) for 573 K.

4. **DISCUSSION**

There is now a good understanding of the creep behaviour in coarse-grained metals and alloys. Under steady-state conditions, the creep rate, \( \dot{\varepsilon} \), varies with the applied stress, \( \sigma \), the absolute temperature, \( T \), and the grain size, \( d \), through a relationship of the form

\[
\dot{\varepsilon} = ADGb \left( \frac{b}{d} \right)^p \left( \frac{\sigma}{G} \right)^n
\]

(1)

where \( D \) is the appropriate diffusion coefficient \( |D_0 \exp (-Q/RT)| \) where \( D_0 \) is a frequency factor, \( Q \) is the activation energy and \( R \) is the gas constant, \( G \) is the shear modulus, \( b \) is the Burgers vector, \( k \) is Boltzmann’s constant, \( p \) and \( n \) are the exponents of the inverse grain size and the applied stress, respectively, and \( A \) is a dimensionless constant. Over a wide range of intermediate stresses the creep rate is controlled by intragranular processes so that \( p = 0 \) and there is no dependence on grain size, but at low stresses intergranular creep processes may become important, such as Nabarro-Herring \([15,16]\) and Coble \([17]\) diffusion creep and/or grain boundary sliding \([18]\), and this introduces a dependence on grain size with \( p \geq 1 \).

Only limited reports are available describing the creep behaviour of ultrafine-grained materials mostly processed by severe plastic deformation \([19,20]\). Thus, neither the phenomenological nor the microscopic
aspects of creep deformation and damage of ultrafine-grained materials have been understood sufficiently as yet. By contrast, there has been much research activity related to creep in nanostructured materials processed by electrodeposition. Yin [4] has recently reviewed the available data on creep in such materials. Regardless of an extensive research effort on electrodeposited nickel some contradicting results among different investigators or between experimental results have been published [4,8,21].

It should be emphasized that the limited amount of available present creep data, the scatter in data and the problems of thermal instability make an attempt to determine the creep rate controlling mechanism(s) of materials under investigation unfeasible. The minimum creep rate of both deposits is related to the applied stress through a power-law but the values of the stress exponent n are extremely high for temperature 293 and 373 K, respectively (Fig. 3a). At present there is no detailed explanation for such extremely high values of n at lower temperatures and high applied stresses. However, it cannot be excluded that under such creep loading conditions the creep rate varies exponentially with the applied stress. The point of transition from power-law creep to an exponential form of creep at high stresses is generally termed power-law breakdown. Further, such high stress exponents are typical of almost athermal plastic deformation, below what is usually regarded as a typical creep temperature. It is therefore appropriate to perform the prediction of creep mechanism at 573 K where a number of the experimental points for composite are sufficient to make use of such analysis. Since Coble diffusion creep has been reported frequently in earlier studies, the present experimental data were compared with the calculated Coble creep rate [17] where n = 1 and p = 3 in Eq. (1). Fig. 3a shows the behaviour predicted for Coble diffusion creep rates for different temperatures. The line for Coble creep at 573 K demonstrates that this process is too fast by comparison with experiment. Part of the discrepancy between experiment and theory may be ascribed to the lack of appropriate diffusion data. Furthermore, the experimental data at 573 K do not follow the prediction of Coble creep, since the experimentally determined stress exponent n is substantially greater than 1.

5. CONCLUSION
Creep and microstructure investigations of electrodeposited ultrafine-grained nickel and its particle-reinforced nanocomposite were undertaken to examine creep behaviour and deformation mechanism controlling the creep rate. It was found that the creep resistance of the nanocomposite might be noticeably improved compared to the monolithic nickel. The Coble creep as creep rate controlling mechanism was found improbable. Power-law breakdown as an explanation of high value of stress exponent n at lower temperatures and high applied stresses was suggested.

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